

DA3S101F

Silicon epitaxial planar type

For high speed switching circuits

DA3X101F in SSMini3 package

■ Features

- Small reverse current I_R
- Short reverse recovery time t_{rr}
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	Single	100	mA
	Series	65	mA
Peak forward current	Single	225	mA
	Series	145	mA
Non-repetitive peak forward surge current *	Single	500	mA
	Series	325	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: 1 t = 1 s

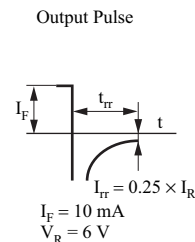
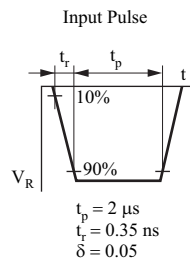
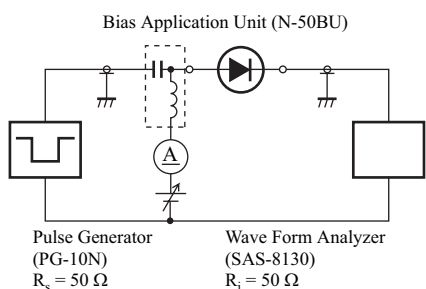
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$		0.92	1.20	V
Reverse voltage	V_R	$I_R = 100 \mu\text{A}$	80			V
Reverse current	I_R	$V_R = 80 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Reverse recovery time *	t_{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{tr} = 0.25 \times I_R$			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

3. *: t_{rr} measurement circuit

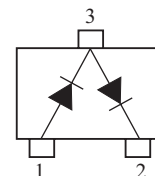


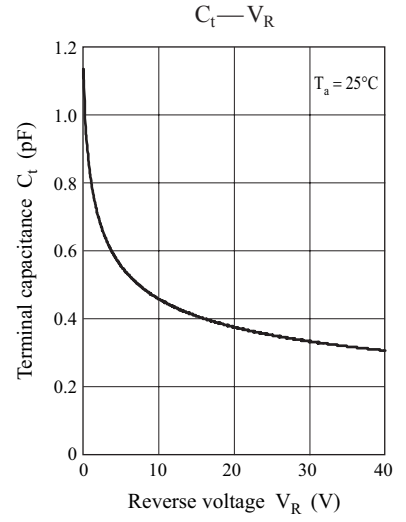
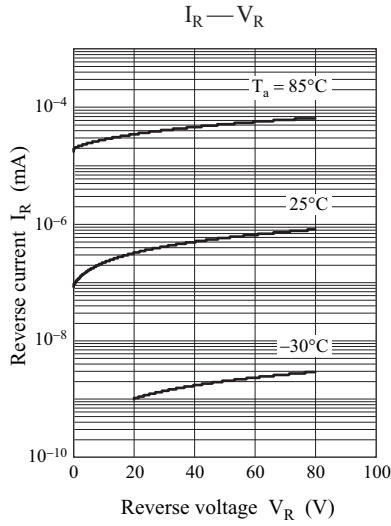
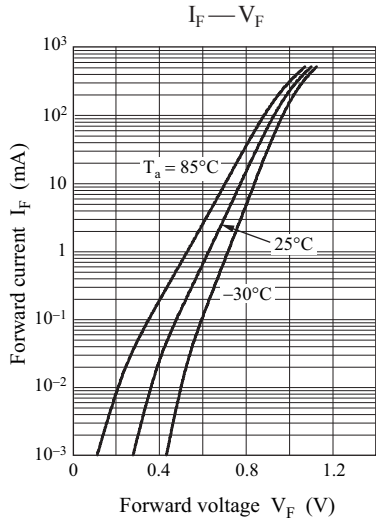
■ Package

- Code
SSMini3-F3-B
- Pin Name
1: Anode-1 3: Cathode-1
2: Cathode-2 Anode-2

■ Marking Symbol: 22

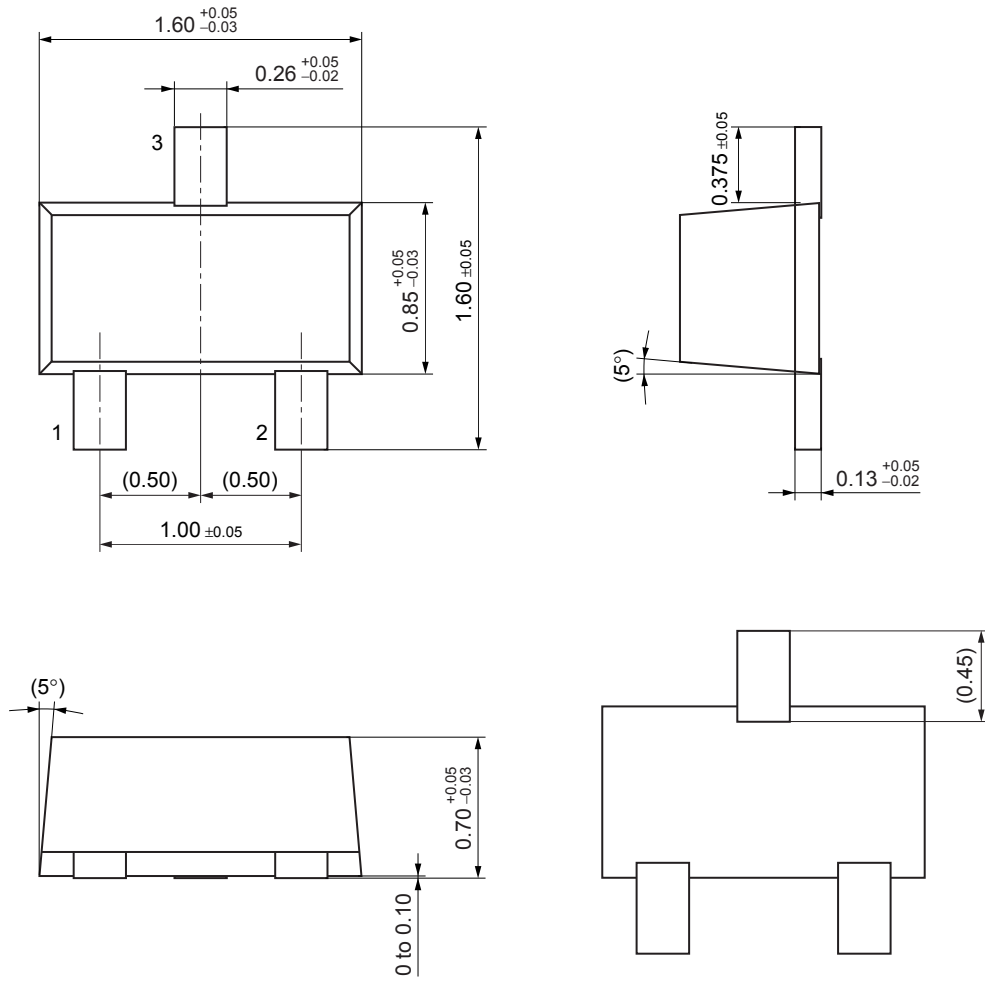
■ Internal Connection





SSMini3-F3-B

Unit: mm



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